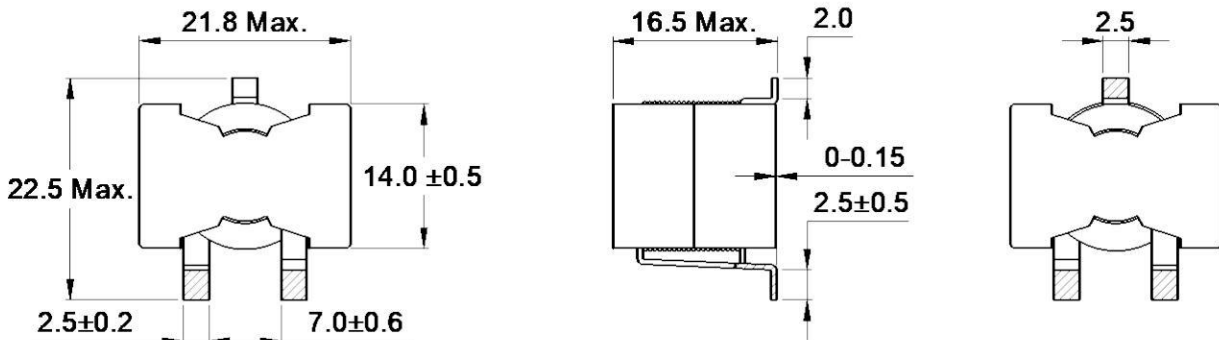




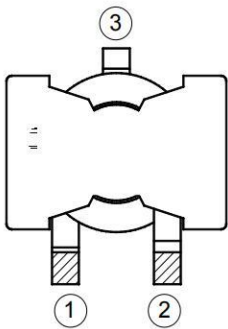
Outline: 产品概要

- Assemblage design, sturdy structure.
组立式设计，结构坚固。
- High inductance, high current, low magnetic loss, low ESR, small parasitic capacitance.
高电感值，大电流，低磁损，低阻抗，寄生电容小。
- Flat wire winding, achieve a low D.C. Resistance.
扁平线绕组，实现极低的直流电阻。
- Low power loss, suitable for applications of wide temperature and frequency range.
低损耗设计，适合宽频宽温环境应用。
- Operating temperature : $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$
(Including coil's temperature rise)
工作温度： $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (包含线圈发热)

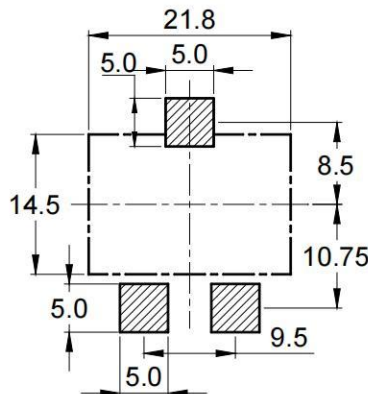
1 Appearance and dimensions (mm) 外形尺寸



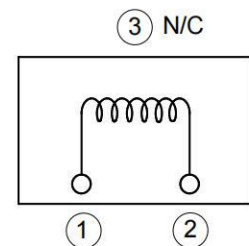
2 Marking 印字标识



3 Reference land pattern (mm) 参考基板尺寸



4 Schematic 原理图



※ Date code will be changed by manufacture date.
生产日期代码将根据生产日期变动。



5 Electrical characteristics

电气特性

Part No. 型号	Inductance (μ H) 电感值 ※1 $\pm 20\%$	D.C.R. ($m\Omega$) 直流电阻		Saturation current (A) 饱和电流 ※2 Typical	Temperature rise current (A) 温升电流 ※3 Typical
		Typical	Max.		
CSCF2016-4R7MC	4.70	3.30	4.00	42.0	21.0
CSCF2016-6R8MC	6.80	3.57	4.30	30.0	20.0
CSCF2016-8R2MC	8.20	3.57	4.30	25.0	20.0
CSCF2016-100MC	10.0	5.28	6.30	24.0	16.0
CSCF2016-220MC	22.0	5.28	6.30	10.0	16.0
CSCF2016-330MC	33.0	13.0	15.0	9.00	12.0
CSCF2016-470MC	47.0	13.0	15.0	6.50	12.0

■ All data is tested based on 25°C ambient temperature.

所有数据基于环境温度 25°C条件下测试。

※1 Inductance measure condition at 100kHz, 0.1V.

电感测试条件为 100kHz, 0.1V。

※2 Saturation current: the actual value of DC current when the inductance decrease 20% of its initial value.

饱和电流: 电感值下降其初始值的 20%时所加载的实际直流电流值。

※3 Temperature rise current: the actual value of DC current when the temperature rise is $\Delta T 40^{\circ}\text{C}$ ($T_a=25^{\circ}\text{C}$).

温升电流: 使产品温度上升到 $\Delta T 40^{\circ}\text{C}$ 时所加载的实际直流电流值($T_a=25^{\circ}\text{C}$)。

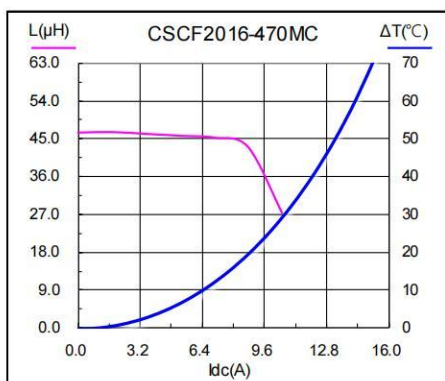
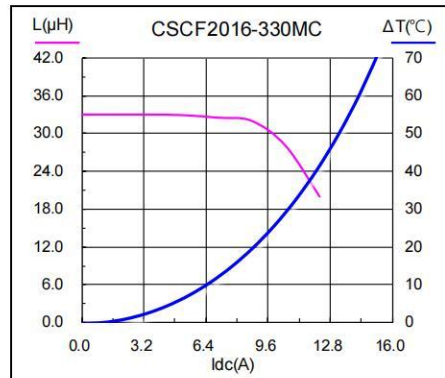
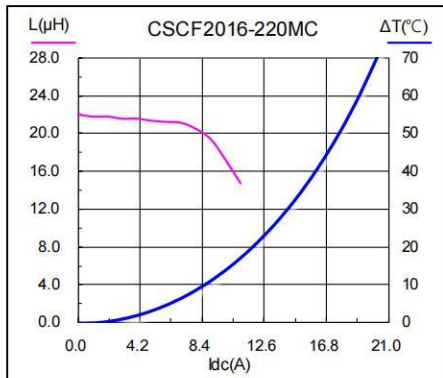
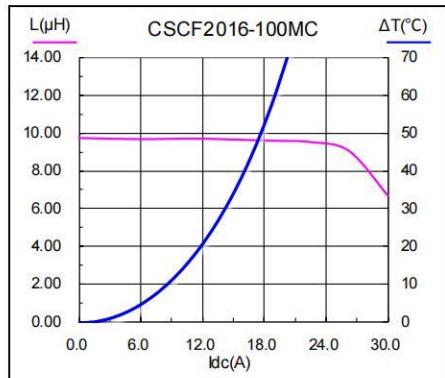
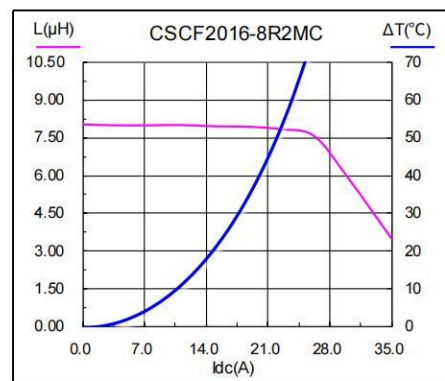
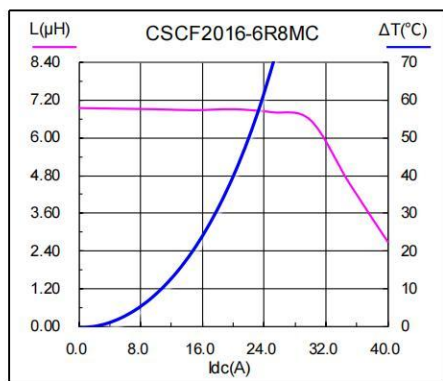
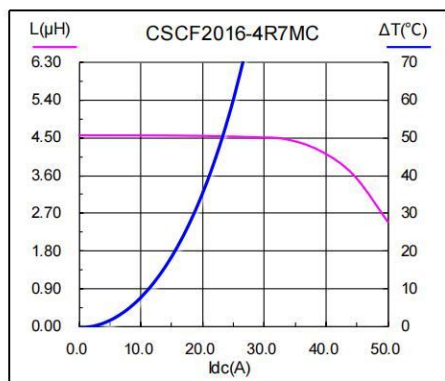
※ Special remind: Circuit design, component placement, PCB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.

特别提醒: 线路设计, 组件布局, 印刷电路板(PCB)尺寸及厚度, 散热系统等均会影响产品温度。

请务必在最终应用时, 验证产品发热状况。



6 Saturation current VS temperature rise current curve 饱和电流 VS 温升电流曲线



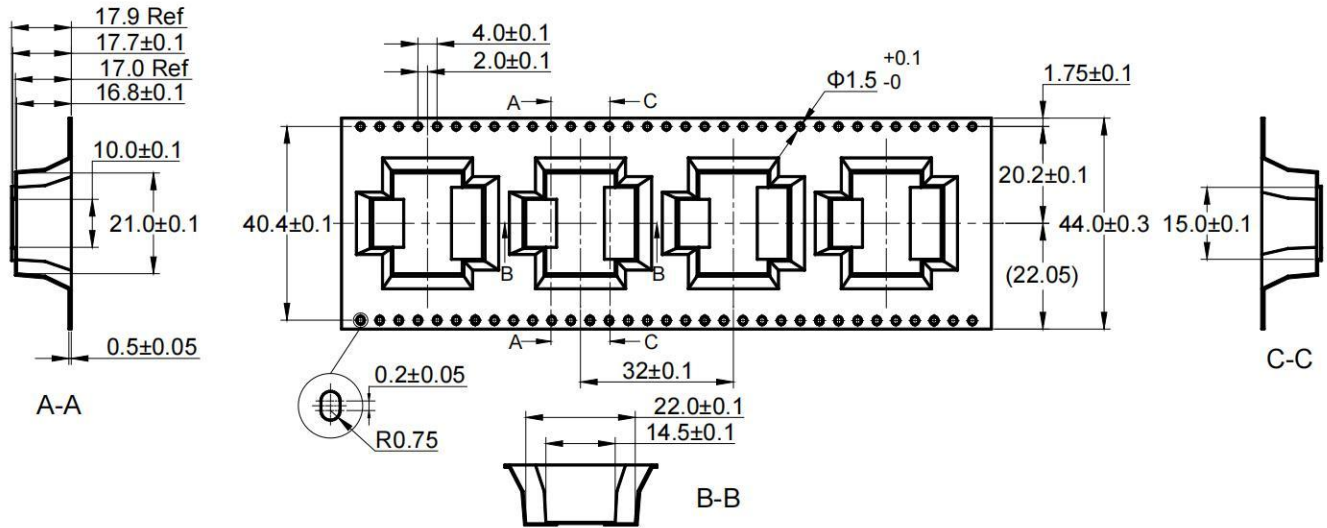


7 Packing specification

包装规格

7.1 Carrier tape dimensions (mm)

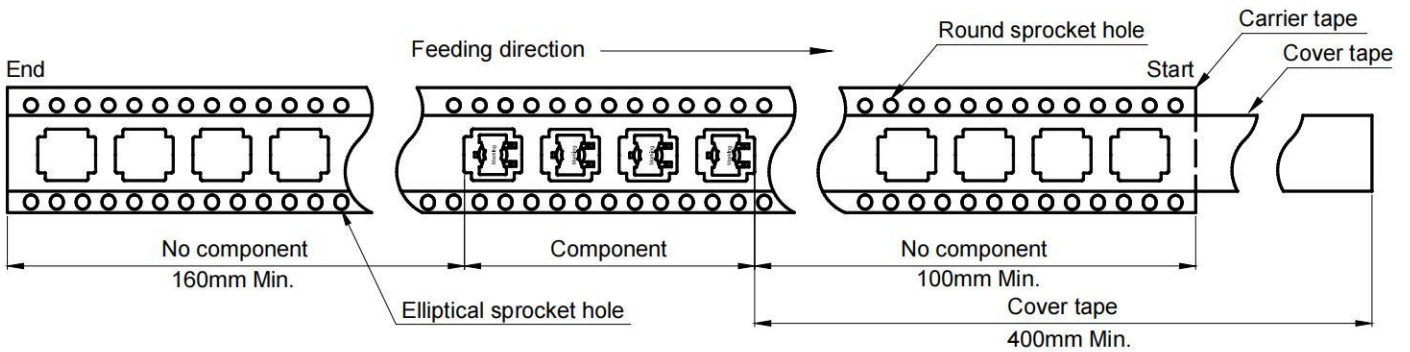
载带尺寸



※ Packing is referred to the international standard IEC 60286-3.
包装参照国际标准 IEC 60286-3。

7.2 Tape direction

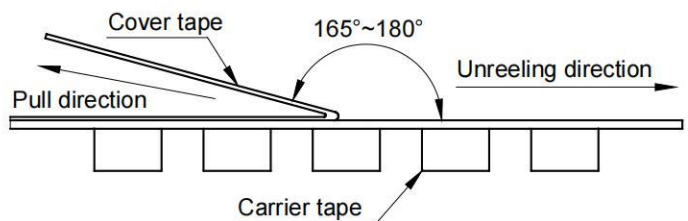
捆包方向



7.3 Cover tape peel off condition

盖带剥离条件

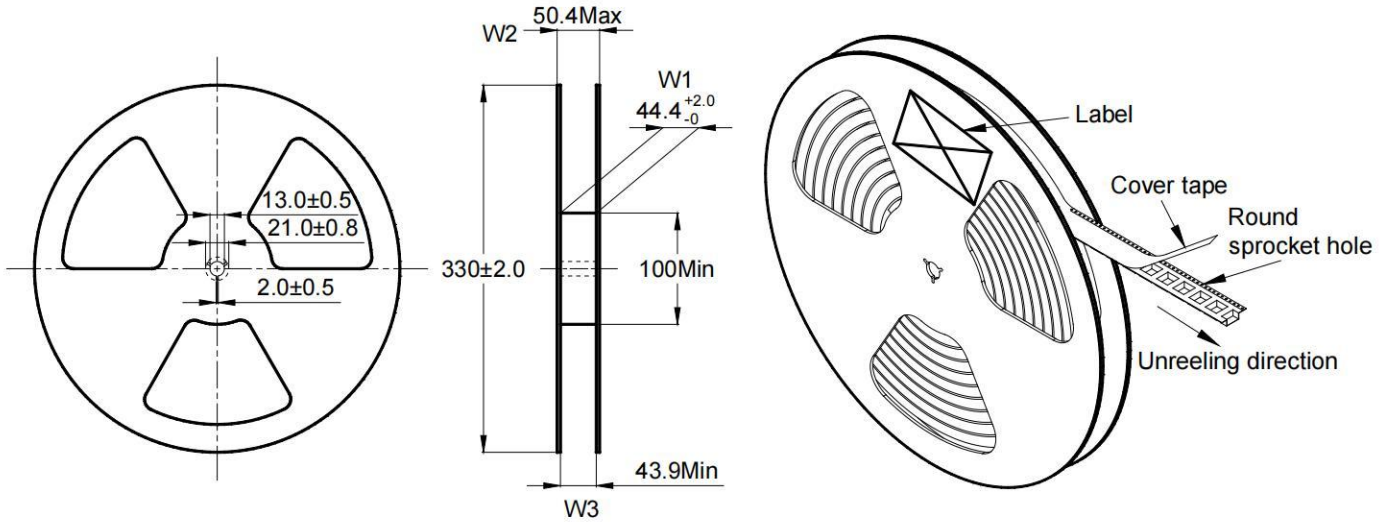
- Cover tape peel force shall be 0.1 to 1.3N.
盖带剥离力度为 0.1~1.3N。
- Reference peel speed 300±10mm/min.
参考剥离速度 300±10mm/分钟。





7.4 Reel dimensions (mm)

卷盘尺寸



7.5 Carton dimensions and packing quantity

包装箱尺寸和包装数量

■ Inner Carton: 340×340×135mm
内包装盒

■ Out Carton : 360×360×295mm
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
CSCF2016	100pcs	(100×2) = 200pcs	(200×2) = 400pcs

7.6 Label making

标签标识

The following items will be marked on the reel of product label and shipping label.
以下项目将明确标识于产品卷盘标签以及运输标签上。

Production Label 产品标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

Shipping Label 运输标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

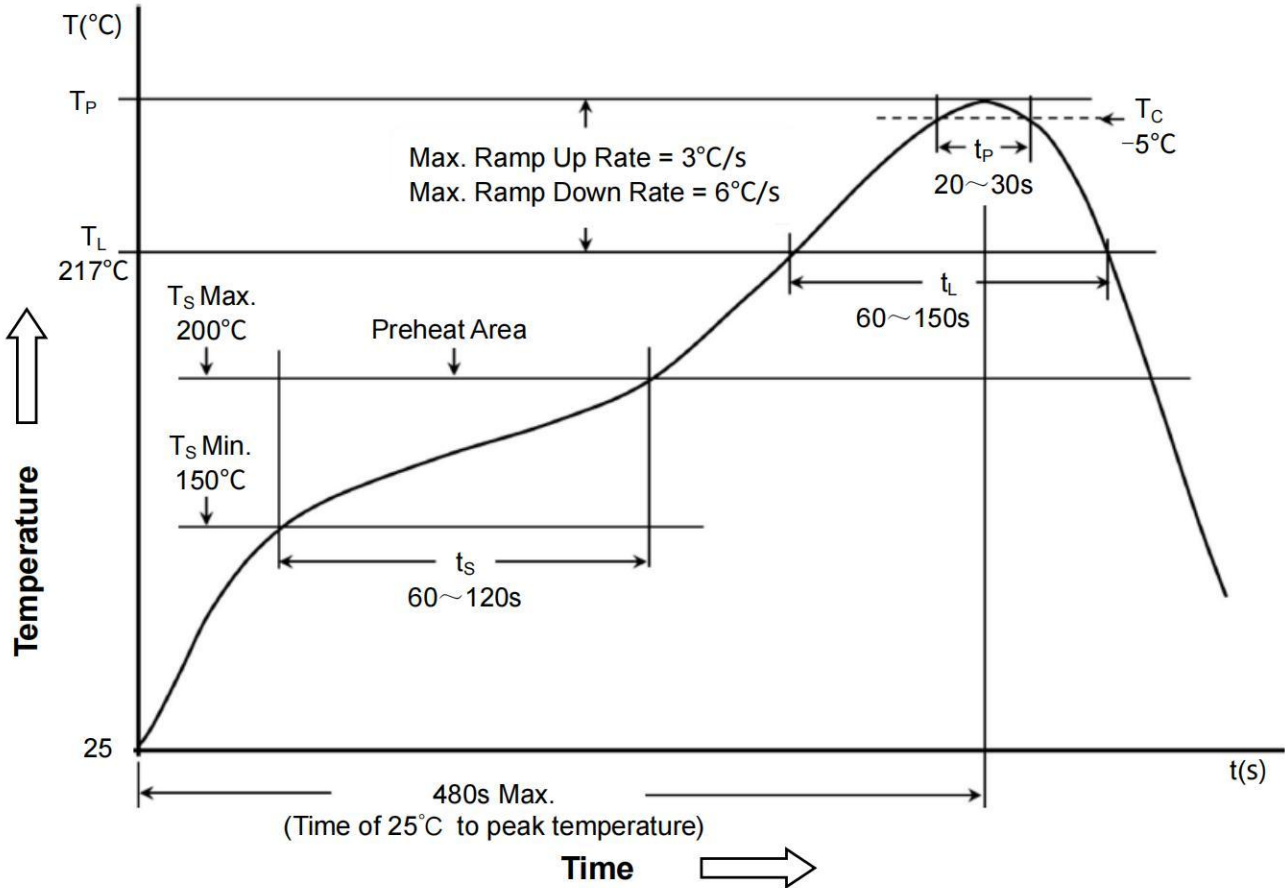


8 Soldering specification

焊接规格

8.1 Reflow profile for SMT components

SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (T_P)

封装体峰值温度(T_P)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		$<350\text{ mm}^3$	$350 \sim 2000\text{ mm}^3$	$>2000\text{ mm}^3$
PB-Free Assembly 无铅装配	$<1.6\text{mm}$	260°C	260°C	260°C
	$1.6 \sim 2.5\text{mm}$	260°C	250°C	245°C
	$\geq 2.5\text{mm}$	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D。